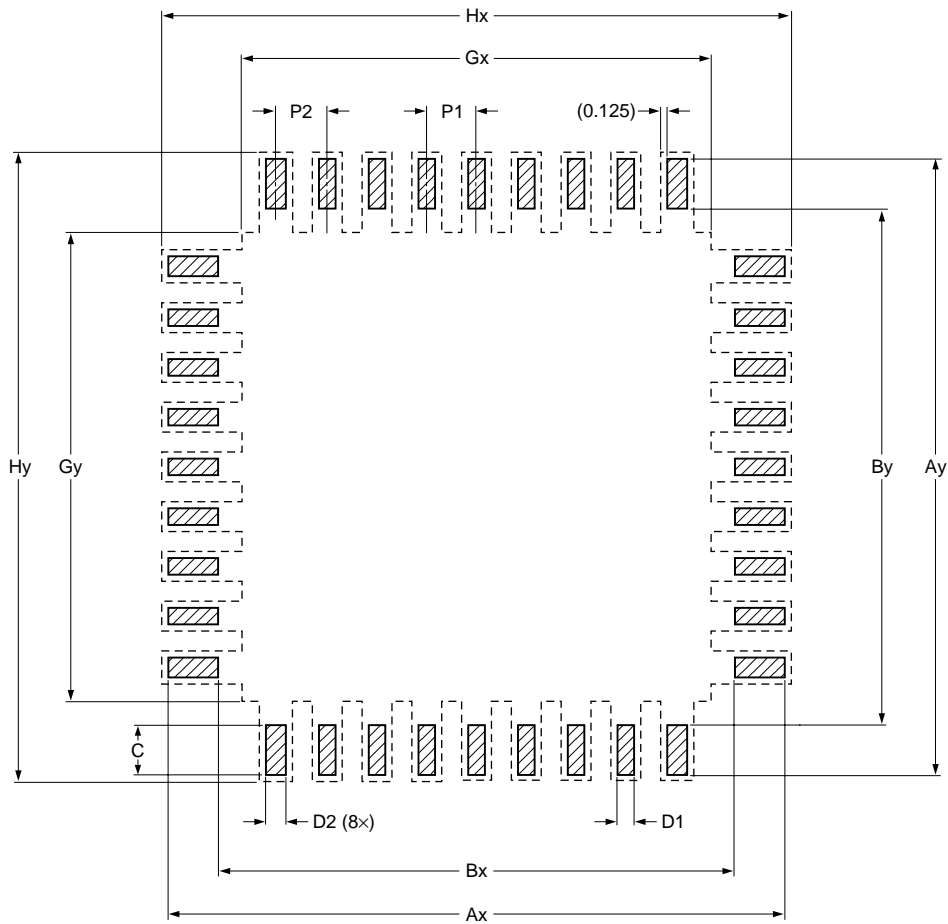




Footprint information for reflow soldering of QFP80 package

SOT318-2



Generic footprint pattern  
Refer to the package outline drawing for actual layout

-  solder land
-  occupied area

DIMENSIONS in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy
0.800	0.850	25.300	19.300	20.900	14.900	2.200	0.500	0.600	20.500	14.500	25.550	19.550